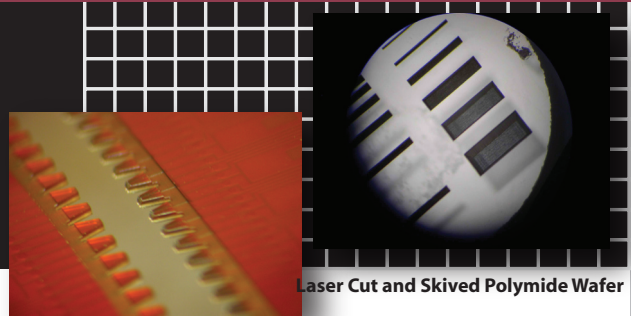


Laser Micromachining and Manufacturing



Laser Cut and Skived Polymide Wafer

Depth Skived and Laser Routed Polymide Part

Ultra Precision Laser Machining for Microelectronics

Capabilities:

- Drill microvias as small as 25µm in almost any material including polyimide, stainless steel, silicon wafers, sapphire, nitinol, and phenolic
- High precision microbeam skives, microscopic grooves, steps, channels or cavities into parts of any substrate
- Scribe numbers, emblems, alignment features or logos
- Create precision polymeric or metallic stencils and masks
- Precision hole drilling for alignment of optical fiber

When precision counts, trust your laser micromachining work to the best team in the business - Quik-Pak. The combination of our highly skilled technicians and advanced laser processing system can create very clean microstructures with sharply defined edges, steep walls and unprecedented precision in just about any material.

Quik-Pak offers the following:

- Silicon wafer coring from wafers as large as 12" (305mm) custom extraction of smaller development wafers.
- Laser cutting, drilling and marking
- Evaluation of product or process feasibility
- Consultation in laser material processing
- Development and optimization of production processes
- Large-volume jobs
- Pilot and short-run production
- Test samples and prototypes
- File translation for CAM
- Laser Stencils

In the world of high-density microelectronics packaging, precision is everything. That is why Quik-Pak has invested in state-of-the-art laser machining technology, offering unparalleled accuracy for all your micromachining needs.

Quik-Pak

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